- Designed for Complementary Use with the BD242 Series
- 40 W at 25°C Case Temperature
- 3 A Continuous Collector Current
- 5 A Peak Collector Current
- Customer-Specified Selections Available

Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING			VALUE	UNIT
	BD241		55	
Collector-emitter voltage (R _{RF} = 100 Ω)	BD241A	\/	70	V
Collector-entitler voltage (N _{BE} = 100 sz)	BD241B	V _{CER}	90	V
	BD241C		115	
	BD241		45	
Collector-emitter voltage (I _C = 30 mA)	BD241A	\/	60	V
	BD241B	V _{CEO}	80	
	BD241C		100	
Emitter-base voltage		V _{EBO}	5	V
Continuous collector current		I _C	3	Α
Peak collector current (see Note 1)			5	Α
Continuous base current			1	Α
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)			40	W
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)			2	W
Unclamped inductive load energy (see Note 4)		½LI _C ²	32	mJ
Operating junction temperature range			-65 to +150	°C
Storage temperature range			-65 to +150	°C
Lead temperature 3.2 mm from case for 10 seconds			250	°C

NOTES: 1. This value applies for $t_p \le 0.3$ ms, duty cycle $\le 10\%$.

- 2. Derate linearly to 150°C case temperature at the rate of 0.32 W/°C.
- 3. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.
- 4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH, $I_{B(on)}$ = 0.4 A, R_{BE} = 100 Ω , $V_{BE(off)}$ = 0, R_S = 0.1 Ω , V_{CC} = 20 V.



BD241, BD241A, BD241B, BD241C NPN SILICON POWER TRANSISTORS

JUNE 1973 - REVISED MARCH 1997

electrical characteristics at 25°C case temperature

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C = 30 mA (see Note 5)	I _B = 0	BD241 BD241A BD241B BD241C	45 60 80 100			V
I _{CES}	Collector-emitter cut-off current	V _{CE} = 55 V V _{CE} = 70 V V _{CE} = 90 V V _{CE} = 115 V	$V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$	BD241 BD241A BD241B BD241C			0.2 0.2 0.2 0.2	mA
I _{CEO}	Collector cut-off current	V _{CE} = 30 V V _{CE} = 60 V	I _B = 0 I _B = 0	BD241/241A BD241B/241C			0.3 0.3	mA
I _{EBO}	Emitter cut-off current	V _{EB} = 5 V	I _C = 0				1	mA
h _{FE}	Forward current transfer ratio	$V_{CE} = 4 V$ $V_{CE} = 4 V$	I _C = 1 A I _C = 3 A	(see Notes 5 and 6)	25 10			
V _{CE(sat)}	Collector-emitter saturation voltage	I _B = 0.6 A	I _C = 3 A	(see Notes 5 and 6)			1.2	>
V_{BE}	Base-emitter voltage	V _{CE} = 4 V	I _C = 3 A	(see Notes 5 and 6)			1.8	V
h _{fe}	Small signal forward current transfer ratio	V _{CE} = 10 V	$I_{C} = 0.5 \text{ A}$	f = 1 kHz	20			
h _{fe}	Small signal forward current transfer ratio	V _{CE} = 10 V	$I_{C} = 0.5 \text{ A}$	f = 1 MHz	3			

NOTES: 5. These parameters must be measured using pulse techniques, t_p = 300 μ s, duty cycle \leq 2%.

thermal characteristics

	PARAMETER			MAX	UNIT
$R_{\theta J}$	C Junction to case thermal resistance			3.125	°C/W
$R_{\theta J}$	A Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

		PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
Ī	t _{on}	Turn-on time	I _C = 1 A	$I_{B(on)} = 0.1 A$	$I_{B(off)} = -0.1 A$		0.3		μs
Ī	t _{off}	Turn-off time	$V_{BE(off)} = -3.7 \text{ V}$	$R_L = 20 \Omega$	$t_p = 20 \ \mu s, \ dc \le 2\%$		1		μs

 $^{^{\}dagger} \ \ \mbox{Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.}$

PRODUCT INFORMATION

^{6.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

TYPICAL CHARACTERISTICS

TYPICAL DC CURRENT GAIN VS COLLECTOR CURRENT $T_{CS631AH}$ $T_{C} = 25^{\circ}C$ $T_{C} = 80^{\circ}C$ $T_{C} = 80^{\circ}C$

Figure 1.

COLLECTOR-EMITTER SATURATION VOLTAGE

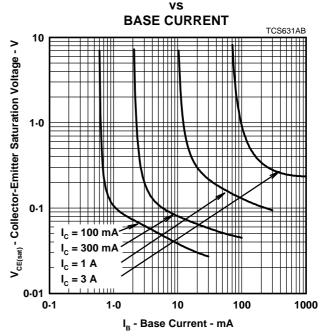


Figure 2.

BASE-EMITTER VOLTAGE

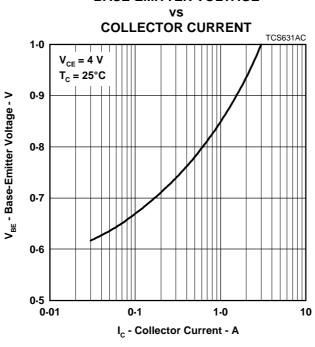
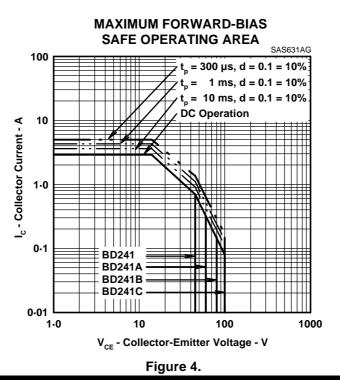


Figure 3.

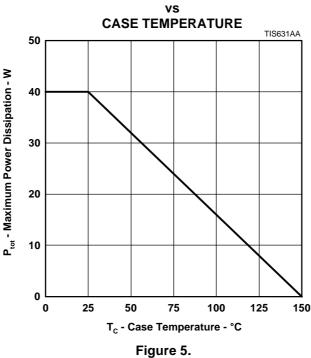


MAXIMUM SAFE OPERATING REGIONS



THERMAL INFORMATION

MAXIMUM POWER DISSIPATION



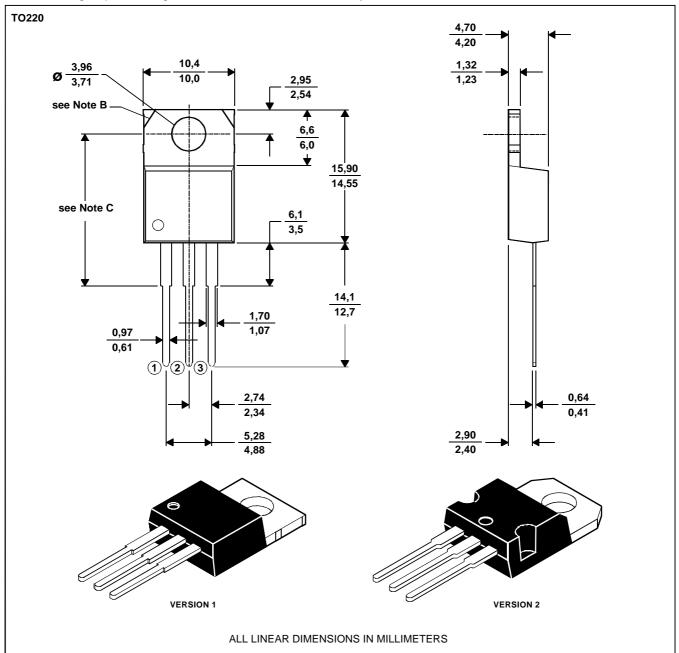
PRODUCT INFORMATION

MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm. MDXXBE



BD241, BD241A, BD241B, BD241C NPN SILICON POWER TRANSISTORS

JUNE 1973 - REVISED MARCH 1997

IMPORTANT NOTICE

Power Innovations Limited (PI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to verify, before placing orders, that the information being relied on is current.

PI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with PI's standard warranty. Testing and other quality control techniques are utilized to the extent PI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except as mandated by government requirements.

PI accepts no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor is any license, either express or implied, granted under any patent right, copyright, design right, or other intellectual property right of PI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS.

Copyright © 1997, Power Innovations Limited